

Title (en)

Method and apparatus for abrasive slurry distribution in mechanical polishing of substrate

Title (de)

Verfahren und Vorrichtung zur Abgabe von Poliermittel -Aufschlämmung im mechanischen Polieren von Substraten

Title (fr)

Dispositif et procédé de distribution de suspension abrasive pour le polissage mécanique de substrat

Publication

**EP 0980741 B1 20021113 (FR)**

Application

**EP 99401715 A 19990708**

Priority

FR 9810508 A 19980818

Abstract (en)

[origin: EP0980741A1] The apparatus for distribution of abrasive suspension or slurry comprises a reservoir (1) in a recirculation contour (40) with pumps (5,6) and a filter (8), and a flow control system including a pressure sensor (80) and a proportional integral-differential (PID) block (81) electrically connected to pumps. The apparatus also includes a refilling reservoir (42), a reservoir (44) for an inert gas under pressure as e.g. nitrogen (N<sub>2</sub>) of high purity, and valves (70,71,72) in lines to user terminals. The flow velocity in the distribution system is within the limits 0.2-10 m/s, preferably 0.5-2 m/s or 1-1.2 m/s. The two pumps (5,6) are connected in parallel, each operating at 50 % of power with possibility of 100 % in the case of breakdown of one pump. The distribution system also contains the means for vaporization of deionized water in gas under pressure to prevent blockage of filters. In another embodiment, the apparatus comprises two reservoirs for abrasive suspension connected in parallel, and a control system with the pressure sensor, the PID block, and additional controlled valves and level sensors.

IPC 1-7

**B24B 37/04**; **B24B 57/02**

IPC 8 full level

**B24B 57/00** (2006.01); **B24B 37/04** (2012.01); **B24B 57/02** (2006.01)

CPC (source: EP KR US)

**B24B 37/04** (2013.01 - EP US); **B24B 57/00** (2013.01 - KR); **B24B 57/02** (2013.01 - EP US); **Y10T 137/4673** (2015.04 - EP US); **Y10T 137/469** (2015.04 - EP US); **Y10T 137/4807** (2015.04 - EP US)

Designated contracting state (EPC)

DE GB IT NL

DOCDB simple family (publication)

**EP 0980741 A1 20000223**; **EP 0980741 B1 20021113**; CN 1139106 C 20040218; CN 1247381 A 20000315; DE 69903893 D1 20021219; DE 69903893 T2 20031009; FR 2782506 A1 20000225; FR 2782506 B1 20000922; JP 2000071173 A 20000307; JP 4970635 B2 20120711; KR 100601812 B1 20060719; KR 20000017362 A 20000325; SG 75972 A1 20001024; TW 411289 B 20001111; US 6125876 A 20001003

DOCDB simple family (application)

**EP 99401715 A 19990708**; CN 99111787 A 19990811; DE 69903893 T 19990708; FR 9810508 A 19980818; JP 23031099 A 19990817; KR 19990034072 A 19990818; SG 1999003470 A 19990708; TW 88112864 A 19990729; US 22349798 A 19981229